



General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

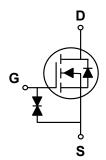
BV _{DSS}	R _{DS(ON)}	Ι _D
55 V	1.6 Ω	320 mA

Features

- $R_{DS(ON)} \le 1.6 \Omega @V_{GS} = 10V$
- Improved dv/dt Capability
- · Fast Switching
- · Green Device Available
- ESD Protected

SOT-323 Pin Configuration





Applications

- Notebook
- · Load Switch
- · Battery Protection
- Hand-Held Instruments

Symbol	Parameter Rating		
V_{DS}	Drain-Source Voltage	55	V
V_{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current - Continuous	320	mA
I _{DM}	Drain Current - Pulsed (NOTE 1)	1800	mA
P_D	Power Dissipation (T _A =25°C)	300	mW
T_J	Operating Junction Temperature Range	-50 to 150	°C
T _{STG}	Storage Temperature Range	-50 to 150	°C

Thermal Characteristics				
Symbol	Parameter	Rating	Unit	
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	417	°C/W	





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	55			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} =55V , V_{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±10	uA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =300mA			1.6	
		V _{GS} =4.5V , I _D =200mA			2.5	Ω
		V _{GS} =2.5V , I _D =100mA			4.5	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	0.8		1.5	V
gfs	Forward Transconductance	V _{DS} =10V , I _D =250mA		400		mS

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge	V_{DS} =15V , V_{GS} =5V , I_{D} =200mA			1	nC
$T_{d(on)}$	Turn-On Delay Time	V_{DD} =30V , V_{GS} =10V , R_L =150 Ω		1.3		nS
$T_{d(off)}$	Turn-Off Delay Time	, R_G =10 Ω , I_D =200mA		5.5		113
C _{iss}	Input Capacitance	V _{DS} =25V , V _{GS} =0V , F=1MHz			50	
C _{oss}	Output Capacitance			7		pF
C_{rss}	Reverse Transfer Capacitance			4		

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V, Force Current			320	mA
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =320mA			1.2	V
T _{rr}	Reverse Recovery Time	V_{GS} =0V , V_{DD} =30V , I_{S} =1A ,		14.4		nS
Q_{rr}	Reverse Recovery Charge	dls/dt=100A/us		5.8		nC

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 3. Essentially independent of operating temperature.





Characteristics Curves

FIG. 1-Output Characteristic

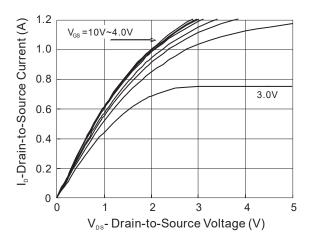


FIG. 2-Transfer Characteristic

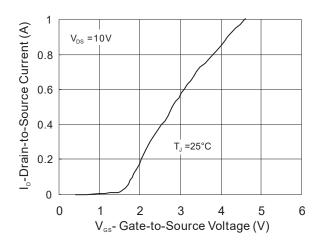


FIG. 3-On-Resistance vs Drain Current

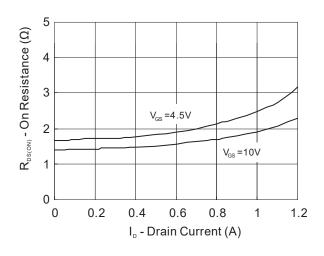


FIG. 4-On-Resistance vs Gate to Source Voltage

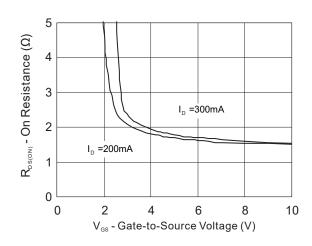


FIG. 5-On-Resistance vs Junction Temperature

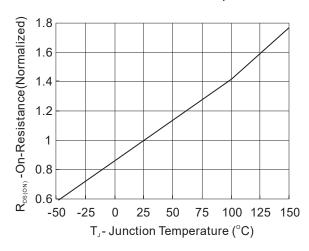
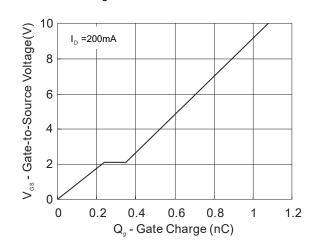


FIG. 6-Gate Charge Waveform







Characteristics Curves

FIG. 7-Source-Drain Diode Forward Voltage

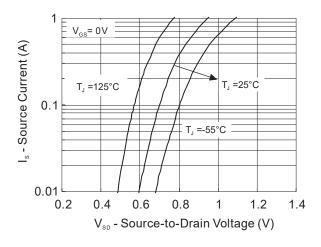


FIG. 8-Threshold Voltage vs Temperature

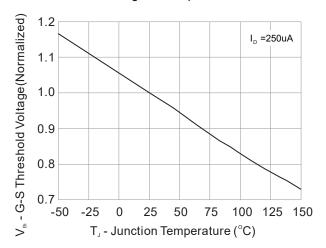
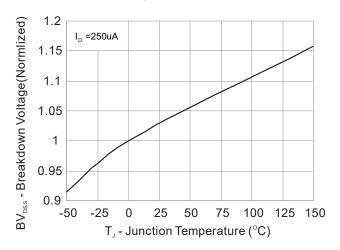
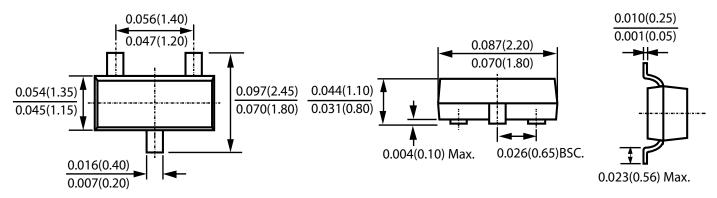


FIG. 9-Breakdown Voltage vs Junction Temperature



Package Outline Dimensions



SOT-323

Dimensions in inches and (millimeters)





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